

# NUP1301ML3T1, SZNUP1301ML3T1

## Low Capacitance Diode Array for ESD Protection in a Single Data Line

NUP1301ML3T1 is a MicroIntegration device designed to provide protection for sensitive components from possible harmful electrical transients; for example, ESD (electrostatic discharge).

### Features

- Low Capacitance (0.9 pF Maximum)
- Single Package Integration Design
- Provides ESD Protection for JEDEC Standards JESD22  
Machine Model = Class C  
Human Body Model = Class 3B
- Protection for IEC61000-4-2 (Level 4)  
8.0 kV (Contact)  
15 kV (Air)
- Ensures Data Line Speed and Integrity
- Fewer Components and Less Board Space
- Direct the Transient to Either Positive Side or to the Ground
- AEC-Q101 Qualified and PPAP Capable
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- Pb-Free Package is Available\*

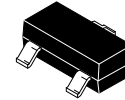
### Applications

- T1/E1 Secondary IC Protection
- T3/E3 Secondary IC Protection
- HDSL, IDSL Secondary IC Protection
- Video Line Protection
- Microcontroller Input Protection
- Base Stations
- I<sup>2</sup>C Bus Protection

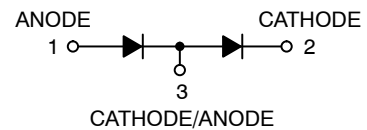


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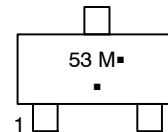
<http://onsemi.com>



SOT-23  
CASE 318  
STYLE 11



### MARKING DIAGRAM



53 = Device Code  
M = Date Code  
■ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
NUP1301ML3T1	SOT-23	3,000 / Tape & Reel
NUP1301ML3T1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
SZNUP1301ML3T1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# NUP1301ML3T1, SZNUP1301ML3T1

## MAXIMUM RATINGS (Each Diode) ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Reverse Voltage	$V_R$	70	Vdc
Forward Current	$I_F$	215	mAdc
Peak Forward Surge Current	$I_{FM(surge)}$	500	mAdc
Repetitive Peak Reverse Voltage	$V_{RRM}$	70	V
Average Rectified Forward Current (Note 1) (averaged over any 20 ms period)	$I_{F(AV)}$	715	mA
Repetitive Peak Forward Current	$I_{FRM}$	450	mA
Non-Repetitive Peak Forward Current $t = 1.0 \mu\text{s}$ $t = 1.0 \text{ms}$ $t = 1.0 \text{S}$	$I_{FSM}$	2.0 1.0 0.5	A

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 =  $1.0 \times 0.75 \times 0.062$  in.

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	625	$^\circ\text{C/W}$
Lead Solder Temperature Maximum 10 Seconds Duration	$T_L$	260	$^\circ\text{C}$
Junction Temperature	$T_J$	-65 to 150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-65 to +150	$^\circ\text{C}$

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise noted) (Each Diode)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>					
Reverse Breakdown Voltage ( $I_{(BR)} = 100 \mu\text{A}$ )	$V_{(BR)}$	70	-	-	Vdc
Reverse Voltage Leakage Current ( $V_R = 70 \text{Vdc}$ ) ( $V_R = 25 \text{Vdc}$ , $T_J = 150^\circ\text{C}$ ) ( $V_R = 70 \text{Vdc}$ , $T_J = 150^\circ\text{C}$ )	$I_R$	-	-	2.5 30 50	$\mu\text{Adc}$
Diode Capacitance (between I/O and ground) ( $V_R = 0$ , $f = 1.0 \text{MHz}$ )	$C_D$	-	-	0.9	pF
Forward Voltage ( $I_F = 1.0 \text{mAdc}$ ) ( $I_F = 10 \text{mAdc}$ ) ( $I_F = 50 \text{mAdc}$ ) ( $I_F = 150 \text{mAdc}$ )	$V_F$	-	-	715 855 1000 1250	$\text{mV}_{dc}$

2. FR-5 =  $1.0 \times 0.75 \times 0.062$  in.

3. Alumina =  $0.4 \times 0.3 \times 0.024$  in, 99.5% alumina.

## NUP1301ML3T1, SZNUP1301ML3T1

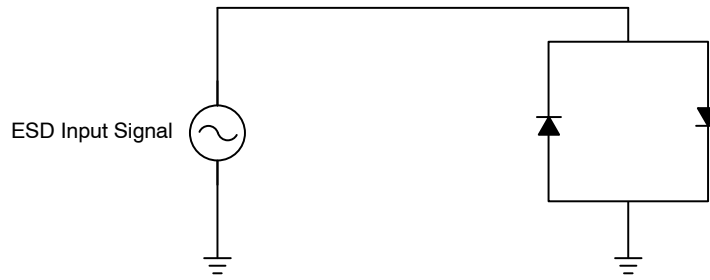


Figure 1. ESD Test Circuit

### APPLICATION NOTE

#### Electrostatic Discharge

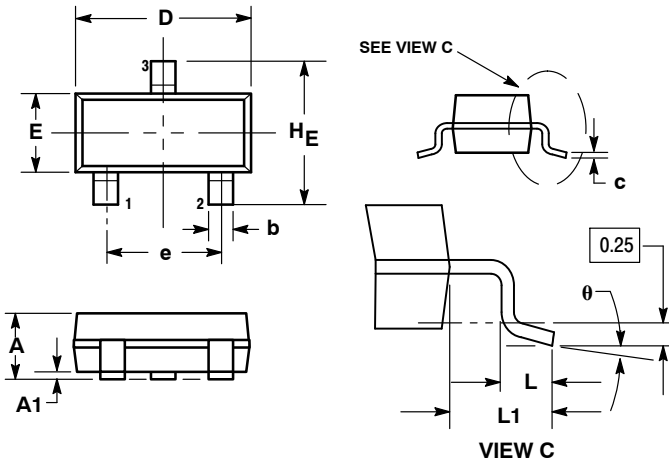
A common means of protecting high-speed data lines is to employ low-capacitance diode arrays in a rail-to-rail configuration. Two devices per line are connected between two fixed voltage references such as  $V_{CC}$  and ground. When the transient voltage exceeds the forward voltage ( $V_F$ ) drop of the diode plus the reference voltage, the diodes direct the

surge to the supply rail or ground. This method has several advantages including low loading capacitance, fast response time, and inherent bidirectionality (within the reference voltages). See Figure 1 for the test circuit used to verify the ESD rating for this device.

# NUP1301ML3T1, SZNUP1301ML3T1

## PACKAGE DIMENSIONS

SOT-23 (TO-236)  
CASE 318-08  
ISSUE AP



NOTES:

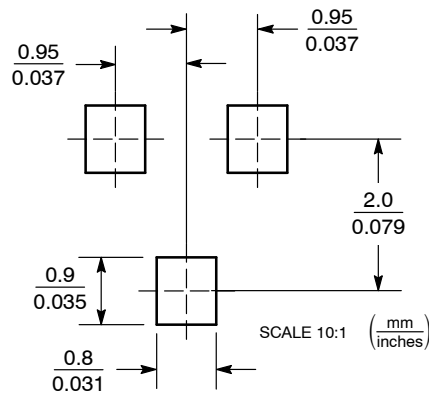
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°	---	10°	0°	---	10°

STYLE 11:

1. ANODE
2. CATHODE
3. CATHODE-ANODE

### SOLDERING FOOTPRINT



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NUP1301ML3T1/D